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Application Number	10/571,246
Filing Date	December 5, 2006
First Named Inventor	Rudhard et al.
Art Unit	2829
Examiner Name	Ming Hung HUNG
Attorney Docket Number	10191/4346

**U.S. PATENT DOCUMENTS**

Examiner Initials *	Cite No. <sup>1</sup>	Document Number Number - Kind Code <sup>2</sup> (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear

**FOREIGN PATENT DOCUMENTS**

Examiner Initials *	Cite No. <sup>1</sup>	Foreign Patent Document Country Code <sup>3</sup> - Number <sup>4</sup> - Kind Code <sup>5</sup> (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T <sup>6</sup>

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		B. TILLACK et al., "Monitoring of Deposition and Dry Etching of Si/SiGe Multiple Stacks", J. Vac. Sci. Technol. B14(1), Jan/Feb 1996, 1996 American Vacuum Society, pp. 102-105.	*
		C.S. PREMACHANDRAN et al., "A Novel Electrically Conductive Wafer Through Hole Filled Vias Interconnect For 3D MEMS Packaging", 2003 Electronic Components and Technology Conference, pp. 627-630.	

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